

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
11 July 2002 (11.07.2002)

PCT

(10) International Publication Number
WO 02/054838 A1

(51) International Patent Classification⁷: **H05K 1/11, 3/34**

(21) International Application Number: PCT/US01/44721

(22) International Filing Date:
28 November 2001 (28 11 2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/751,614 29 December 2000 (29 12.2000) US

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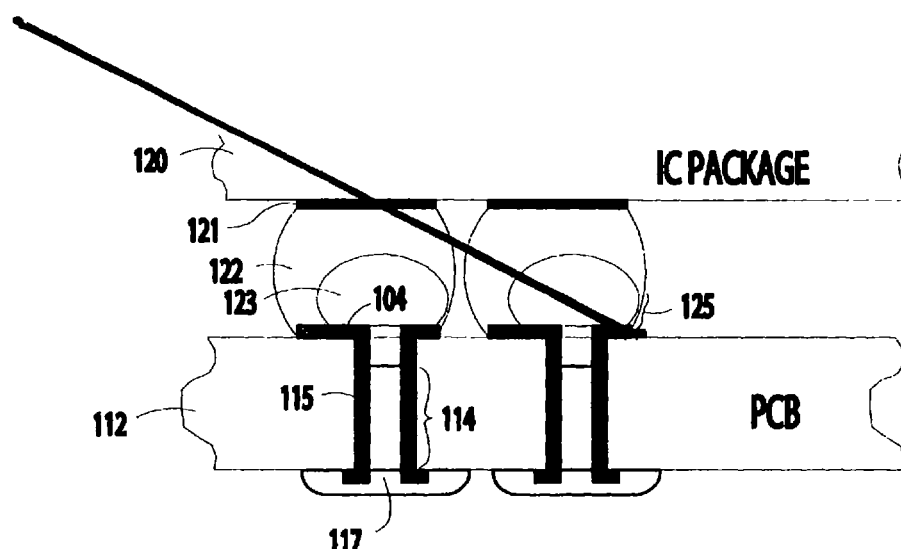
(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)

Published:
— with international search report

[Continued on next page]

(54) Title: VIA-IN-PAD WITH OFF-CENTER GEOMETRY AND METHODS OF MANUFACTURE



(57) Abstract: The electrical contacts (122) of an integrated circuit (120) are coupled to printed circuit board (PCB) bonding pads (104) that include vias (115). A method for fabricating an electronic assembly utilizes at least one operation in which a thermally expansive substance, such as a volatile organic compound (VOC), is applied to the PCB. Some of the VOC (114) goes into the via channels (115). The electrical contacts (122) of a surface mount technology component such as a ball grid array (BGA) solder ball component (120) are affixed to the bonding pads (104) using a reflow soldering technique. According to one embodiment, the vias (115) are formed off-center, so as to inhibit bridging between adjacent solder balls (122) during a solder reflow operation by minimizing the effect of solder ball ballooning (123) resulting from outgassing of the VOC from the via channels (115). A substrate and an electronic system are also described.

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